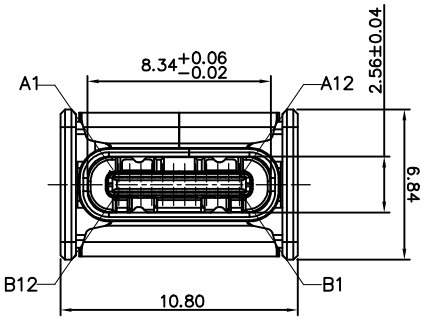
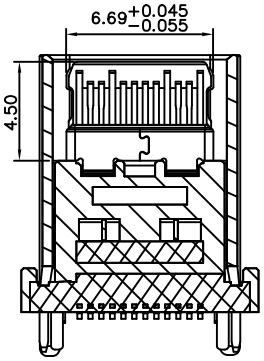
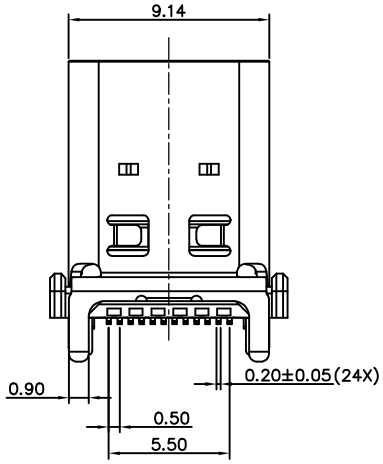
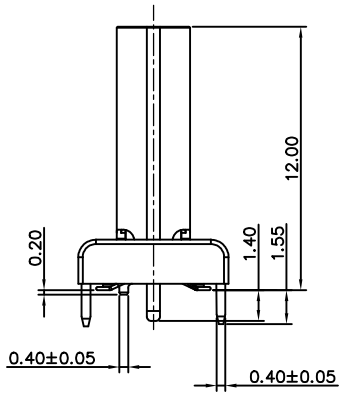
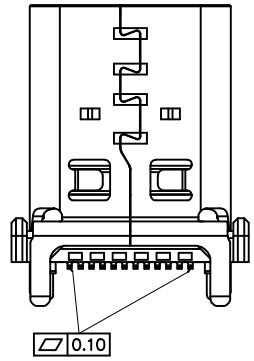




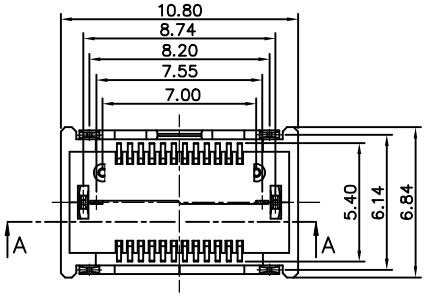
SECTION: A–A

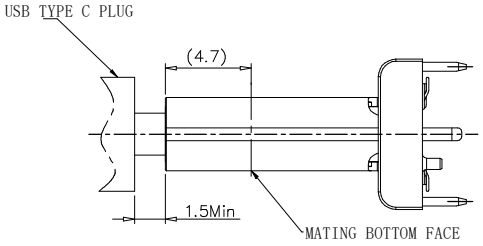






SOLDER TAIL(ALL)





NOTE:
1.MATERIAL SPECIFICATION:
 1.HOUSING: TEMPERATURE RESISTANT PLASTIC,UL94 V–0
 2.TERMINAL: COPPER ALLOY
 3.MID PLATE: STAINLESS STEEL
 4.EMI: STAINLESS STEEL
 5.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:
 2–1.TERMINAL:
  Ni 50u" MIN. UNDER PLATED OVER ALL.
  Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
  (GOLD PLATING THICKNESS FOLLOW THE P/N)
  Au G/F PLATING SPECIFICATIONS OF THE SOLDER AREA
 2–2.EMI&SHELL:
  Ni 30u" MIN. UNDER PLATED OVER ALL.
 2–3.MID PLATE:
  CLEAR ONLY

3.MECHANICAL PERFORMANCE,
 3–1.INSERTION FORCE: 0.5~2.0kgf.
 3–2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 3–3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,
 4–1. VOLTAGE RATING: 5 V DC/AC (RMS. max)
  CURRENT RATING: 5 AMPS. FOR TOTAL VBUS/GND PINS;
  1.25AMPS FOR CC PIN,0.25 AMPS. FOR ALL OTHER CONTACT.
 4–2. LLCR:
  SHIELD: 50mΩ/MAX.
  LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 4–3.INSULATION RESISTANCE: 100MΩ MIN
 4–4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: −25°C~+85°C.

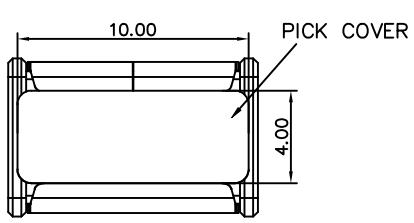
6.IR REFLOW:
 THE PEAK TEMPERATURE ON THE BOARD SHALL
 BE MAINTAINED FOR 10 SECONDS AT 260°C.

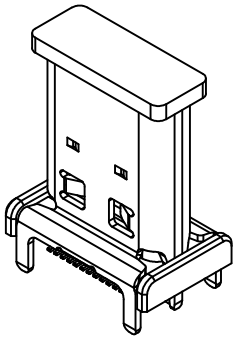
7.PRODUCT PART NUMBER DESCRIPTION:
 10198102 – 0 0 0 X X LF
  LEAD FREE
  PACKING TYPE:
  1: TAPE/REEL
  CONTACT AREA PLATING
  1: GOLD FLASH
  2: 15u" GOLD
  3: 30u" GOLD

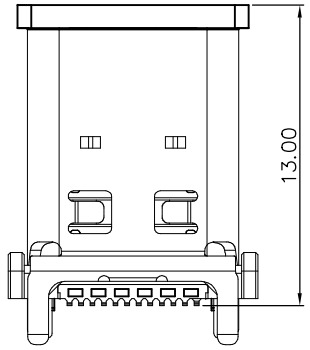
mat'l. code				surface ISO 1302		tolerance ISO 406 ISO 1101		projection	product family		
ltr	ecn no	dr	date	tolerances unless otherwise specified					HPL 511		
A	–	TY.Tang	2026/05/27	angles	linear	0.X±0.35		mm	title		
B	ELX-N-297791	TY.Tang	2026/07/16	0°±x'		0.XX±0.25			USB TYPE C VERTICAL		
						0.XXX±0.15		scale 1:1	24PIN SMT TYPE		
				dr	TY.Tang	2026/07/16			dwg no 10198102	sheet 1 of 2	size A3
				engr	TY.Tang	2026/07/16	Amphenol FCi				
				chr	LQ LEI	2026/07/16					
				appd	TIM YAO	2026/07/16			type Product Customer Drawing		
sheet index	revision sheet	B 1									

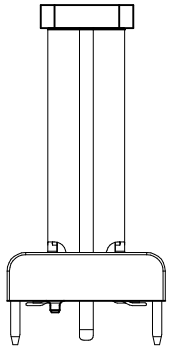
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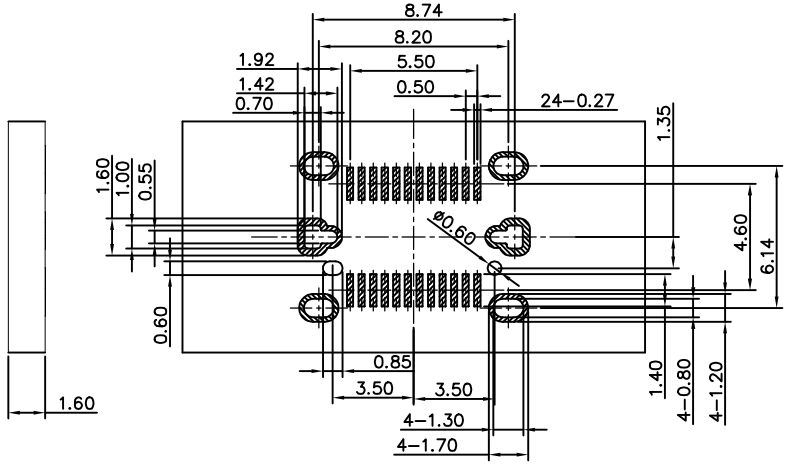
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RECOMENDED PCB LAYOUT
TOL: ±0.05

PIN DEFINE

Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	GND	Ground return	First	B12	GND	Ground return	First
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	Second	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair	Second
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	Second	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair	Second
A4	VBUS	Bus Power	First	B9	VBUS	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SBU2	Sideband Use(SBU)	Second
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	Second	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2	Second
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	Second	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2	Second
A8	SBU1	Sideband Use(SBU)	Second	B5	CC2	Configuration Channel	Second
A9	VBUS	Bus Power	First	B4	VBUS	Bus Power	First
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	Second	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair	Second
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	Second	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair	Second
A12	GND	Ground return	First	B1	GND	Ground return	First

mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family: HPL 511
ltr	ecn no	dr	date	tolerances unless otherwise specified			
B				angles 0°±x°	linear 0.X±0.35 / 0.XX±0.25 / 0.XXX±0.15	mm	title: USB TYPE C VERTICAL 24PIN SMT TYPE
						scale 1:1	
				dr TY.Tang 2026/07/16			dwg no 10198102 sheet 2 of 2 size A3
				engr TY.Tang 2026/07/16		Amphenol FCi	
				chr LQ LEI 2026/07/16			
				appd TIM YAO 2026/07/16			type Product Customer Drawing
sheet index	revision sheet	B 2					

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